Product / Package Information

Package	PDIP
Body Size	300 mils
Lead Count	24
Terminal Finish	100Sn

Environmental Compliance Information

RoHS Compliant	Yes
High Temperature Compliant	Yes
Halogen Free Compliant	Yes
REACH SVHC Compliant	Yes

Materials Declaration

Molding Compound

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Silica	60676-86-0	1.12 E+00	87.7	877000	71.98	719797
Thermosets	Epoxy Resin	Proprietary	6.41 E-02	5.0	50000	4.10	41037
Thermosets	Phenol Resin	Proprietary	6.41 E-02	5.0	50000	4.10	41037
Thermosets	Epoxy Cresol Novolac	29690-82-2	2.56 E-02	2.0	20000	1.64	16415
Other inorganic materials	Carbon Black	1333-86-3	3.84 E-03	0.3	3000	0.25	2462
Subtotal			1.28 E+00	100	1000000	82.07	820749

Leadframe

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Copper & its alloys	Copper	7440-50-8	2.33 E-01	97.50	975000	14.92	149204
Copper & its alloys	Iron	7439-89-6	5.61 E-03	2.35	23500	0.36	3596
Copper & its alloys	Zinc	7440-66-6	2.87 E-04	0.12	1200	0.02	184
Copper & its alloys	Phosphorus	7723-14-0	7.17 E-05	0.03	300	0.00	46
Subtotal			2.39 E-01	100.00	1000000	15.30	153030

Internal Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	1.11 E-03	100.0	1000000	0.07	708

External Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Tin & its alloys	Tin	7440-31-5	2.65 E-02	100.0	1000000	1.70	16954

Bond Wires

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Gold	7440-57-5	2.95 E-04	99.99	1000000	0.02	189

Chip

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Doped Silicon	7440-21-3	1.23 E-02	100.0	1000000	0.79	7879

Die Attach

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	6.14 E-04	80	800000	0.04	393
Thermosets	Epoxy Resin	Proprietary	1.15 E-04	15	150000	0.01	74
Others	Curing agent & hardene	Proprietary	3.83 E-05	5	50000	0.00	25
Subtotal			7.67 E-04	100	1000000	0.05	491

	Weight (g)	Percentage (%)	PPM
Package Totals	**1.56 E+00**	**100.00**	**1000000**

Note: The information provided in this declaration are true to the best of ADI's knowledg
ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liabili
any inaccuracy of such information

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